

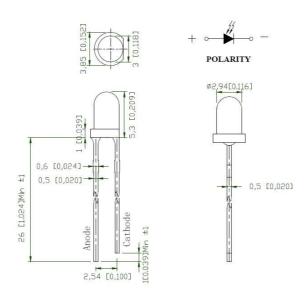
Features

- Low power consumption
- General purpose leads
- Bulk, Available on tape and reel
- Fast response time
- High photo sensitivity
- Small junction capacitance
- Compliance with EU REACH
- The product itself remain within RoHS compliant version

Applications

- High speed photo detector
- Automatic door sensor
- Security system
- Industrial equipment
- Infrared application system

Package Dimensions in mm



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25 mm (.010 $_{"}$) unless otherwise noted.

Figure 1. INL-3APD80 Package Dimensions

Description

- The INL-3APD80 is a high speed and high sensitive silicon PIN photodiode in a standard 3mm epoxy package.
- Due to its clear epoxy, the device is sensitive to near and infrared radiation.



Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
VR	Reverse Voltage	32	V	1
Topr	Operating Temperature	-40~+80	°C	
Tstg	Storage Temperature	-40~+85	°C	
Tsol	Soldering Temperature	260	°C	2
PD	Total Power Dissipation	150	mW	

Notes

- 1. Test conditions : IR=100 μ A, Ee=0mW/cm₂.
- 2. Soldering time \leq 5 seconds.

Electro-Optical Characteristics

Symbol	Parameters	Test conditions	Min	Тур	Max	Units
λD	Rang of Spectral Bandwidth		400	-	1100	nm
λP	Wavelength of Peak Sensitivity		-	850		nm
Vbr	Reverse Breakdown Voltage	Ee=0mW/cm2 IR=100uA	30	170	-	V
Voc	Open-Circuit Voltage	Ee=1mW/cm ² λ _P =850nm	-	0.4	-	V
lsc	Short-Circuit Current	Ee=1mW/cm² λ⊧=850nm	-	35	-	uA
lо	Dark Current	Ee=0mW/cm ² VR=10V	-	5	30	nA
L	Reverse Light Current	Ee=1mW/cm ² λ _P =850nm, VR=5V	20	35	-	uA
tr	Rise Time	V _R =10V,	-	45	-	uS
tr	Fall Time	RL=100Ω	-	45	-	uS
Ст	Transition Capacitance	Ee=0mW/cm ² f=1MHz, VR=5V		18		pF
20 1/2	Receiving Angle	IF=20mA		80		Deg.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

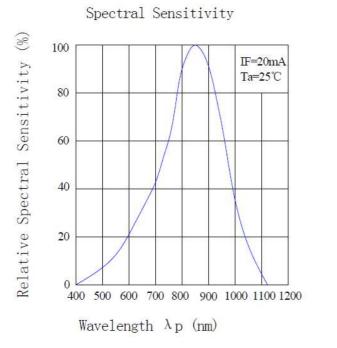
If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).



INL-3APD80 3mm Photodiode Though Hole Lamp LED

Typical Characteristic Curves



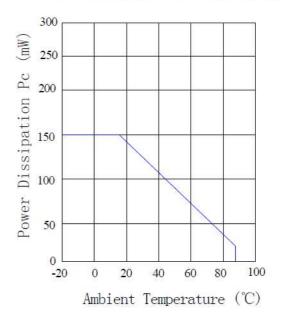
Reverse Dark Current vs. Ambient Temperature 1000 Vr=10V Reverse Dark Current (nA) 100 10 1 60 20 40 80 100

Ambient Temperature Ta(°C)



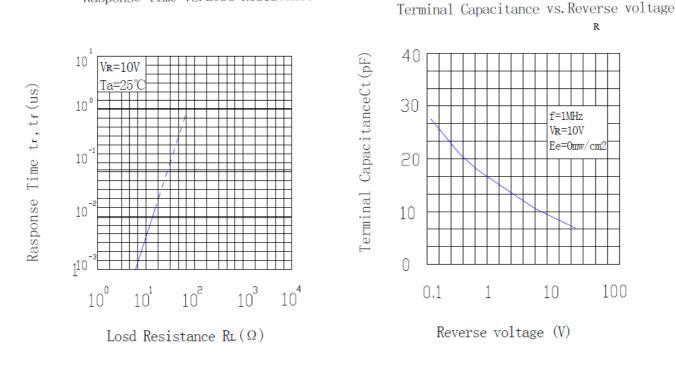
Reverse Light Current vs. Ee

Power Dissipation vs. Ambient Temperature



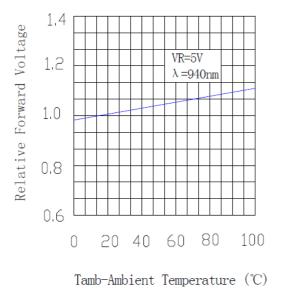
Reverse Light Current (μ A) 60 40 20 $V_R = 5V$ λ=850nm 0 0.1 0.5 1.0 1.5 Ee(mW/cm2)



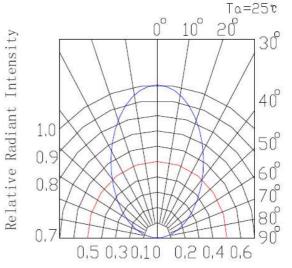


Rasponse Time vs. Losd Resistance

Relative Reverse Light Current vs. Ambient Temperatyre(°C)



Relative Radiant Intensity vs. Angular Displacement





Ordering Information

Product	Symbol	Parameters	Test conditions	Min	Тур	Max	Units	Orderable Part Number
INL-3APD80	L	Reverse Light Current	Ee=1mW/cm ² λ _P =850nm, VR=5V	20	35	-	uA	INL-3APD80

Label Specifications



Inolux P/N:

I	Ν	L	-	3	А	-	PD	8	0	х	х	х	Х
				Pacl	kage	Lens	Color	View A	Angle			mized ıp-off	
	Inolux Lamp Typ	e		stan	۹ = dard nm	(Blank) = clear	PD = Photo Diode	80 = 80) deg.				

Lot No.:

Z	2	0	1	7	01	24	001
Internal		Year (2017	2019 \	Month	Data	Serial	
Tracker		rear (2017	, 2010,)	WOITUI	Date	Serial	



Reliability

Item	Frequency/ lots/ samples/ failures	Standards Reference	Conditions
Precondition	For all reliability monitoring tests according to JEDEC Level 2	J-STD-020	 Baking at 85°C for 24hrs Moisture storage at 85°C/ 60% R.H. for 168hrs
Solderability	1Q/ 1/ 22/ 0	JESD22-B102-B And CNS-5068	Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s
Resistance to soldering heat		CNS-5067	Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s
Operating life test	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs
High humidity, high temperature bias	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs
High temperature bias	1Q/ 1/ 20	IN specs.	Tamb: 55°C IF=20mA Duration: 1000hrs
Pulse life test	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)
Temperature cycle	1Q/ 1/ 76/ 0	JESD-A104-A IEC 68-2-14, Nb	A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type
High humidity storage test	1Q/ 1/ 40/ 0	CNS-6117	60+3°C 90+5/-10% R.H. for 500hrs
High temperature storage test	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs
Low temperature storage test	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	01-24-2019

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